

WHAT IS CLAIMED IS:

1. A bonding method conducted by a bonding device including: a board support table having a plurality of holding portions for individually holding a plurality of boards including at least a first and a second board, the board support table being moved at least in the horizontal direction by a single positioning means; a holding state releasing means for individually releasing a holding state of the board held by the holding portion; a position detecting means for detecting positions of the plurality of boards on the board support table; a plurality of pressure bonding heads arranged corresponding to the respective boards held by the holding portion, for pressure bonding an object to be bonded by pressure to an upper face of each board from an upper portion; and a lower supporting portion for supporting the board from a lower portion in the case of pressure bonding conducted by the pressure bonding head, the bonding method comprising:

a step of detecting the positions of the plurality of boards, which are held on the board support table, by the position detecting means;

a first positioning step of positioning a first board with respect to a first pressure bonding head corresponding to the first board by the positioning means according to a

result of detecting the positions obtained in the step of detecting the positions;

a first pressure bonding step for pressure bonding an object to be bonded by pressure to the first board by the first pressure bonding head when the first board, which has been position, is interposed between the first pressure bonding head and the lower receiving portion;

a first holding state releasing step of releasing a holding state of the first board, which is being bonded by pressure, by the holding state releasing means in the first pressure bonding step;

a second positioning step of positioning the second board to the second pressure bonding head corresponding to the second board by the positioning means according to a result of positional detection obtained in the position detecting step after the first holding state has been released; and

a second pressure bonding step of pressure bonding an object to be bonded by pressure to the second board by the second pressure bonding head corresponding to the second board which has been position.

2. A bonding method according to claim 1, wherein it is judged whether or not it is necessary to execute the first positioning step and the second positioning step

according to the result of positional detection, when it is judged that a positional deviation of the board is in an allowable range, all boards are positioned with respect to the pressure bonding heads corresponding to the respective
5 boards, and when it is judged that a positional deviation of the board exceeds an allowable range, the step proceeds to the first positioning step.

3. A bonding method according to claim 1, wherein
10 the holding portion holds the board by means of vacuum suction.

4. A bonding method according to claim 1, wherein
the board is a display panel, and the object to be bonded
15 by pressure is an adhesive tape.

5. A bonding method according to claim 1, wherein
the board is a display panel, and the object to be bonded
by pressure is an electronic part.